

Wafer UV Resist Hardening System



FEATURES :

- 1.High-intensity ultraviolet irradiation, high throughput
- 2.Min. $650 \text{ m W} / \text{cm}^2$ (at wavelengths ranging from 220 to 450 nm)
- 3.Wafer size : 300 / 200 / 150 mm
- 4.Stage temp.rise / cool rate fast (rise: $2.0 \pm 0.2 \text{ }^\circ\text{C} / \text{sec}$; cool: $3 \text{ }^\circ\text{C} / \text{sec}$)
- 5.UV distribution:Max. $\pm 10 \%$ (measured at 5 points on a wafer in H mode)
- 6.Clean, fast wafer handling
- 7.Space-saving / Complete safety design



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APPLICATIONS :

- 1.Enhancement of thermal resistance of photoresist and degassing from photoresist prior to ion implantation process
- 2.Erasure of electrical charge and removal of stress

SPECIFICATION:

ITEM	SPECIFICATION
Wafer size	Φ300 / 200 / 150 mm
M / C size (W x D x H)	195 X 200 X 250 cm
Power supply	AC 380V / 220V 50 / 60Hz 3 Φ
UV Intensity	Min. 650 m W /cm ² (at wavelengths ranging from 220 to 450 nm)
Max.hot plate temperature	250 °C
Hot-plate temperature rise rate	$T/\Delta t=2.0\pm 0.2^{\circ}\text{C} / \text{sec}$ ($\Delta T\geq 150^{\circ}\text{C}$, H-mode)
Wafer transfer mechanism	Wafer robot
Load port	Manual / Auto
System type	PC BASE MMI
Safety certification	SEMI S2 (option)